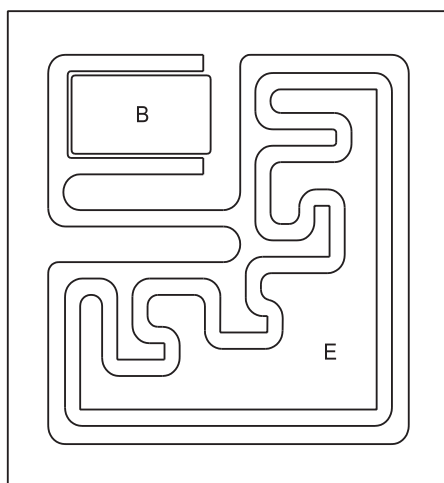


PROCESS DETAILS

Die Size	131 x 131 MILS
Die Thickness	12.5 ±1.0 MILS
Emitter Bonding Pad Area	27 x 36 MILS
Base Bonding Pad Area	20 x 37 MILS
Top Side Metalization	Al - 50,000Å
Back Side Metalization	Ag - 10,000Å

GEOMETRY



R0

BACKSIDE COLLECTOR

PRINCIPAL DEVICE TYPES

2N6059

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R0 (12 -June 2003)